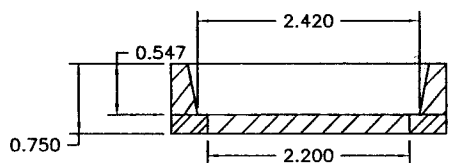
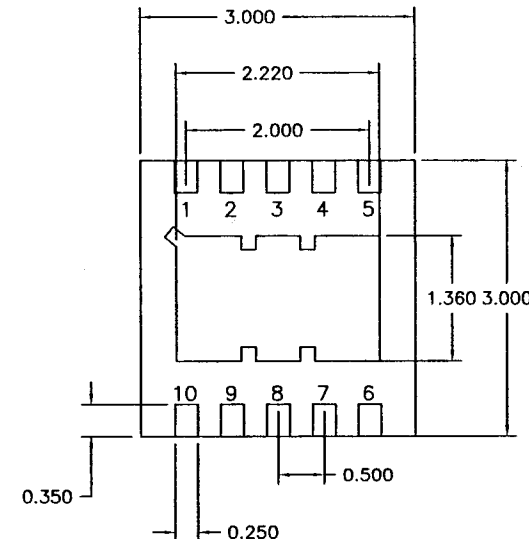
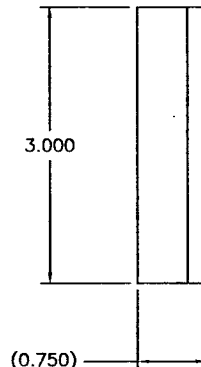
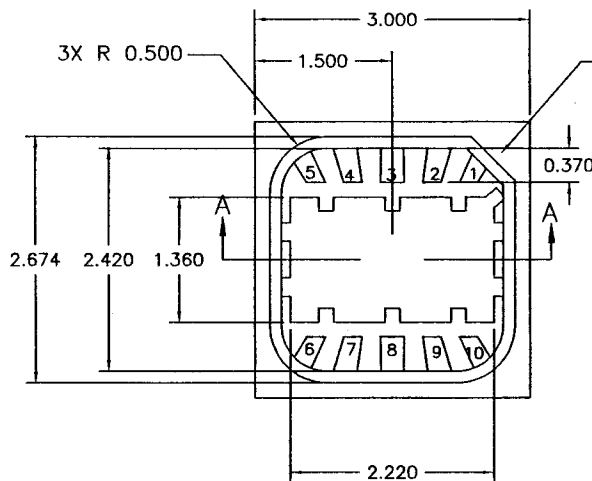


# SSM P/N QFN01001

SEMPAK REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	



**NOTES:**

1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ± 0.0076.
6. DIE PAD: 1.360mm X 2.200mm.
7. JEDEC OUTLINE REFERENCE: MO-229 (VEED-3)

	THIRD ANGLE PROJECTION	DRAWN BY	DATE 12/11/06
	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS	APP BY	DATE 12/11/06
TOLERANCES ARE:		CUSTOMER	
X.XX ± 0.015 X.XXXX ± ---		---	
X.XXX ± 0.050 ANGLES: ± 1°			
DO NOT SCALE DRAWING			

10 LEAD 3mm X 3mm

**QFN3X3-010 REV 1**

